

LTM8042-1 66LD 15mm X 9mm X 2.82mm Epoxy (DA) (TABLE OF MATERIAL DECLARATION)							
The LTM8042 is RoHS compliant per EU RoHS Directive 2003/95/EC.							
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)							
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1300	Barium Compounds	7727-43-7	0.00196	1.51
				Filler Substances (Silica Crystalline)	13776-74-4, 7631-86-9	0.03320	25.53
				Copper Metal	7440-50-8	0.05932	45.62
				Copper Compounds	1328-53-6	0.00003	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00000	0.00
				Gold metal or alloy	7440-57-5	0.00065	0.50
				Nickel	7440-02-0	0.00300	2.31
				Zinc	7440-66-6	0.00004	0.03
				Bismaleimide/Triazine Resin	non-disclosure	0.02609	20.06
				Acrylic Resin	non-disclosure	0.00425	3.27
				Epoxy Resin	non-disclosure	0.00002	0.01
				Chromium(III) Oxide	1308-38-9	0.00000	0.00
				Silica crytalline	14808-60-7	0.00051	0.39
				Silica amorphous	7631-86-9	0.00002	0.02
				Talc;not containing fibers like asbestos	14807-96-9	0.00026	0.20
				Aromatic Carbonyl compounds	non-disclosure	0.00044	0.34
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium caobonate	471-34-1	0.00000	0.00
				Amine compounds	non-disclosure	0.00007	0.05
				Leveling agent and others	non-disclosure	0.00017	0.13
2	Solder Paste	Alloy	0.0078	Sn	7440-31-5	0.00737	95.00
				Sb	7440-36-0	0.00039	5.00
3	Epoxy		0.0002	Di-ester resin	non-disclosure	0.00002	10.00
				Functionalized ester	non-disclosure	0.00002	10.00
				Silver	7440-22-4	0.00012	80.00
4	Passive/Active Components		0.8326	Iron Powder (Fe)	7439-89-6	0.51846	62.27
				Copper (Cu)	7440-50-8	0.29316	35.21
				Nickel (Ni)	7440-02-0	0.00216	0.26
				Tin (Sn)	7440-31-5	0.00175	0.21
				Ceramic (Ba Compounds)	12047-27-7	0.01707	2.05
5	Active Ics	Silicon	0.0040	Silicon	7440-21-3	0.00402	100.00
6	Wire	Gold	0.0008	Au	7440-57-5	0.0008	99.99
7	Encapsulation	Epoxy Resin	0.5065	Fused Silica	60676-86-0	0.39102	77.20
				Epoxy Resin	non-disclosure	0.04508	8.90
				Phenol Resin	non-disclosure	0.04508	8.90
				Crytalline Silica	14808-60-7	0.01520	3.00
				Carbon Black	1333-86-4	0.00253	0.50
				Metal Hydroxide	non-disclosure	0.00760	1.50
Total Package Weight			1.4819				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts